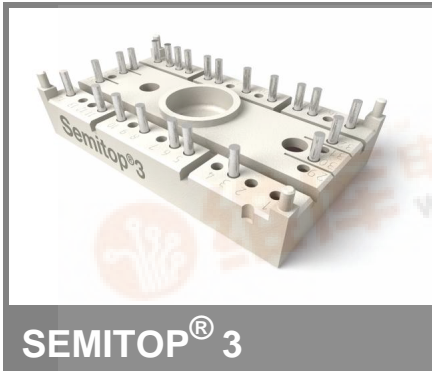


SK50GAL067



SEMITOP® 3

IGBT Module

SK50GAL067

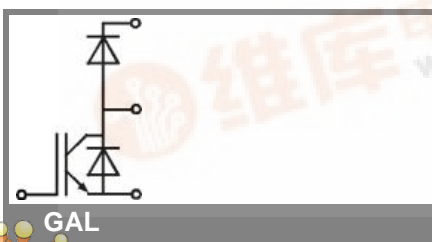
Target Data

Features

- Compact design
- One screw mounting
- Heat transfer and isolation through direct copper bonded aluminium oxide ceramic (DCB)
- Hyperfast NPT technology IGBT
- N-channel homogeneous silicon structure (NPT Non-Punch-Through IGBT)
- Positive $V_{ce,sat}$ temperature coefficient (Easy paralleling)
- Low tail current with low temperature dependence
- Low threshold voltage

Typical Applications

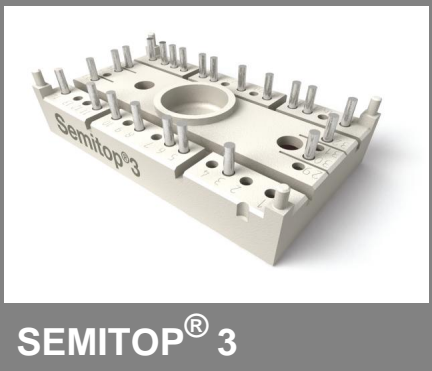
- Switching (not for linear use)
- High Frequencies Applications
- Welding generator
- Switched mode power supplies
- UPS



Absolute Maximum Ratings		$T_s = 25\text{ }^{\circ}\text{C}$, unless otherwise specified		
Symbol	Conditions	Values	Units	
IGBT				
V_{CES}	$T_j = 25\text{ }^{\circ}\text{C}$	600	V	
I_C	$T_j = 125\text{ }^{\circ}\text{C}$	$T_s = 25\text{ }^{\circ}\text{C}$	83	A
		$T_s = 80\text{ }^{\circ}\text{C}$	54	A
I_{CRM}	$I_{CRM} = 2 \times I_{Cnom}$	240	A	
V_{GES}		± 20	V	
t_{psc}	$V_{CC} = 300\text{ V}; V_{GE} \leq 20\text{ V}; T_j = 125\text{ }^{\circ}\text{C}$ $V_{CES} < 600\text{ V}$	10	μs	
Inverse Diode				
I_F	$T_j = 125\text{ }^{\circ}\text{C}$	$T_s = 25\text{ }^{\circ}\text{C}$	90	A
		$T_s = 80\text{ }^{\circ}\text{C}$	56	A
I_{FRM}	$I_{FRM} = 2I_{Fnom}$		A	
I_{FSM}	$t_p = 10\text{ ms}; \text{sinusoidal}$	$T_j = \text{ }^{\circ}\text{C}$	360	A
Freewheeling Diode				
I_F	$T_j = 125\text{ }^{\circ}\text{C}$	$T_{case} = 25\text{ }^{\circ}\text{C}$	90	A
		$T_{case} = 80\text{ }^{\circ}\text{C}$	56	A
I_{FRM}	$I_{FRM} = 2I_{Fnom}$		A	
I_{FSM}	$t_p = 10\text{ ms}; \text{sinusoidal}$	$T_j = \text{ }^{\circ}\text{C}$	360	A
Module				
$I_{t(RMS)}$			A	
T_{vj}		-40 ... +150	$^{\circ}\text{C}$	
T_{stg}		-40 ... +125	$^{\circ}\text{C}$	
V_{isol}	AC, 1 min.	2500	V	

Characteristics		T _s = 25 °C, unless otherwise specified			
Symbol	Conditions	min.	typ.	max.	Units
IGBT					
V _{GE(th)}	V _{GE} = V _{CE} , I _C = 1,2 mA	3	4	5	V
I _{CES}	V _{GE} = 0 V, V _{CE} = V _{CES} T _j = 25 °C			0,008	mA
I _{GES}	V _{CE} = 0 V, V _{GE} = 20 V T _j = 25 °C			480	nA
V _{CE0}	T _j = 150 °C			2	V
r _{CE}	V _{GE} = 15 V T _j = 150°C		13		mΩ
V _{CE(sat)}	I _{Cnom} = 120 A, V _{GE} = 15 V	T _j = 25°C _{chiplev.}		2,8	3,15
		T _j = 125°C _{chiplev.}		3,5	4
C _{ies}	V _{CE} = 25, V _{GE} = 0 V f = 1 MHz			6	nF
C _{oes}				0,6	nF
C _{res}				0,37	nF
t _{d(on)}	R _{Gon} = 6 Ω	V _{CC} = 400V	22		ns
t _r			10		ns
E _{on}	R _{Goff} = 6 Ω	I _{Cnom} = 120A	2,7		mJ
t _{d(off)}		T _j = 125 °C	280		ns
t _f		V _{GE} =±15V	26		ns
E _{off}		1,9		mJ	
R _{th(j-s)}	per IGBT		0,45		K/W

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IGBT Module

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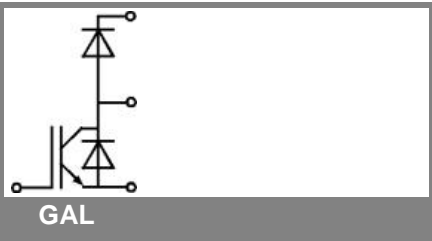
Target Data

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Characteristics						
Symbol	Conditions		min.	typ.	max.	Units
Inverse Diode						
V _F = V _{EC}	I _{Fnom} = 120 A; V _{GE} = 0 V	T _j = 25 °C _{chiplev.}			2	V
		T _j = 125 °C _{chiplev.}		1,25		V
V _{F0}		T _j = 25 °C				V
		T _j = 150 °C		1		V
r _F		T _j = 25 °C				mΩ
		T _j = 150 °C		4		mΩ
I _{RRM} Q _{rr} E _{off}	I _{Fnom} = 120 A di/dt = -100 A/μs V _R =600V	T _j = 125 °C				A μC mJ
R _{th(j-s)D}	per diode				0,8	K/W
Freewheeling Diode						
V _F = V _{EC}	I _{Fnom} = 120 A; V _{GE} = 0 V	T _j = 25 °C _{chiplev.}			2	V
		T _j = 125 °C _{chiplev.}		1,25		V
V _{F0}		T _j = 25 °C				V
		T _j = 150 °C		1		V
r _F		T _j = 25 °C				V
		T _j = 150 °C		4		V
I _{RRM} Q _{rr} E _{off}	I _{Fnom} = 120 A di/dt = -100 A/μs V _R =600V	T _j = 125 °C				A μC mJ
R _{th(j-s)FD}	per diode				0,8	K/W
M _s	to heat sink		2,25		2,5	Nm
w				29		g

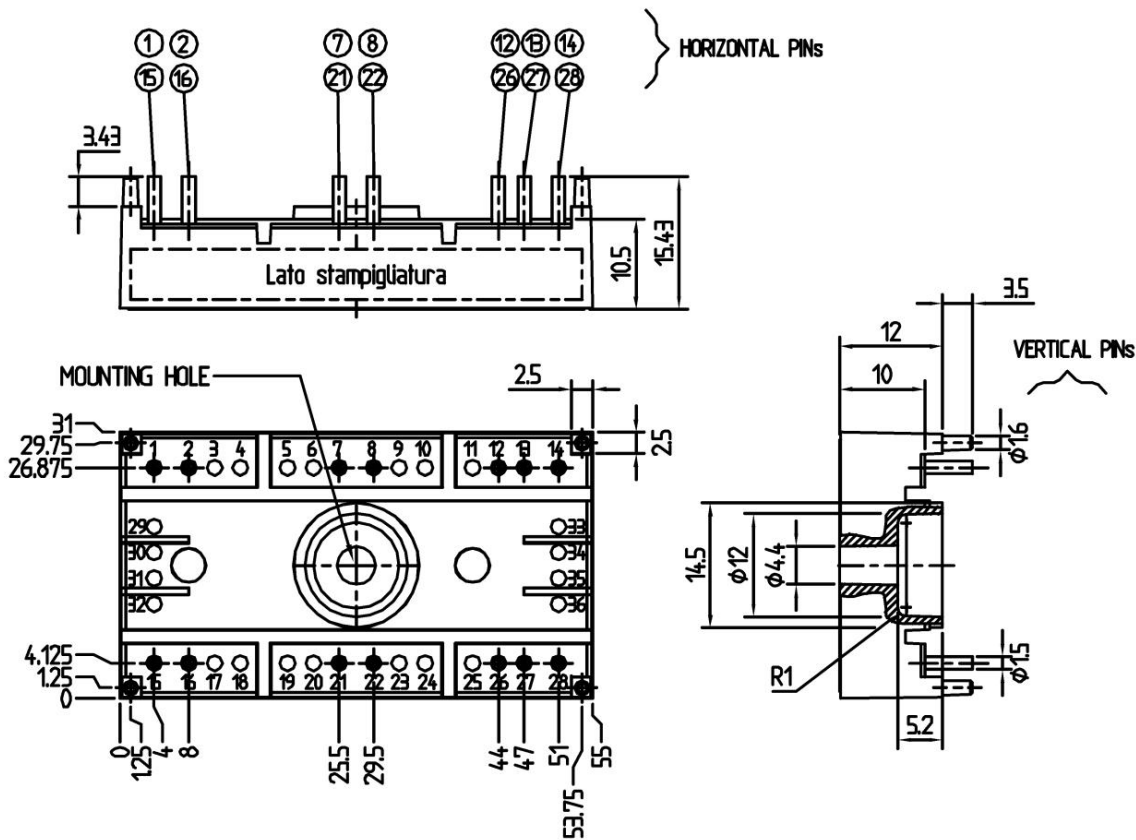
This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

This technical information specifies semiconductor devices but promises no characteristics. No warranty or guarantee expressed or implied is made regarding delivery, performance or suitability.

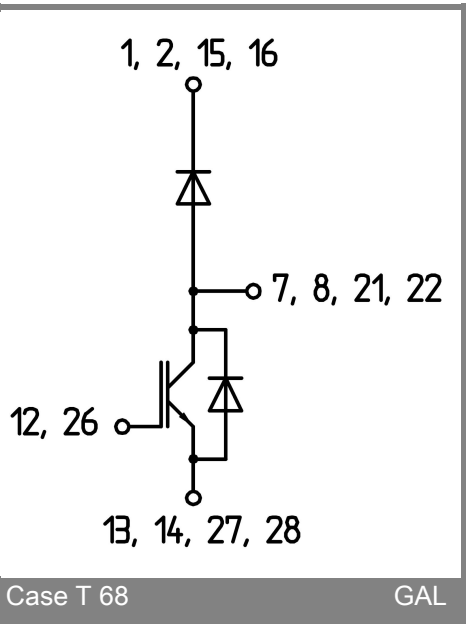
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UL Recognized
File no. E 63 532

Dimensions in mm



Case T68 (Suggested hole diameter, in the PCB, for solder pins and plastic mounting pins: 2mm)



Case T 68

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